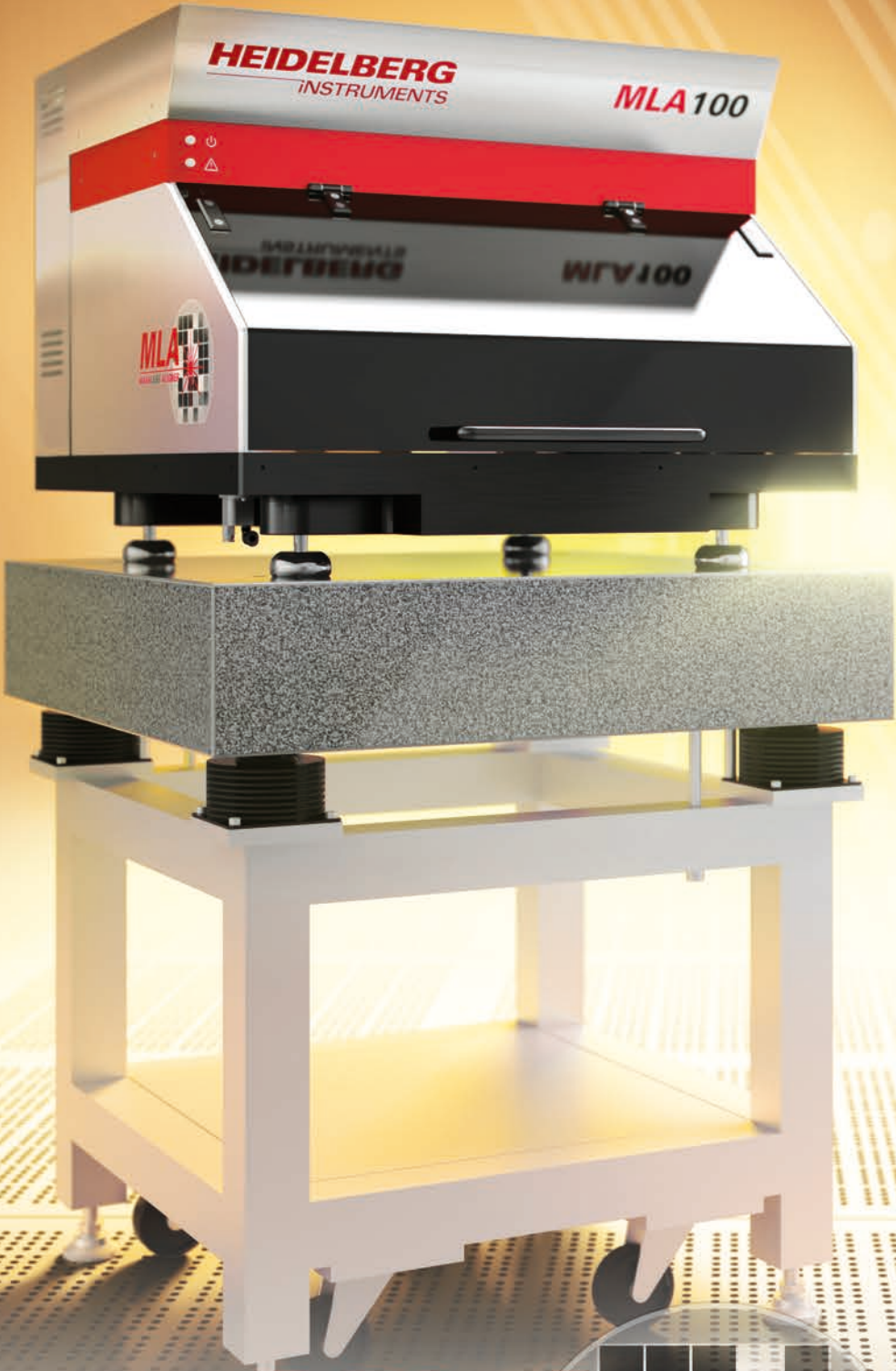


MLA100

HEIDELBERG
INSTRUMENTS



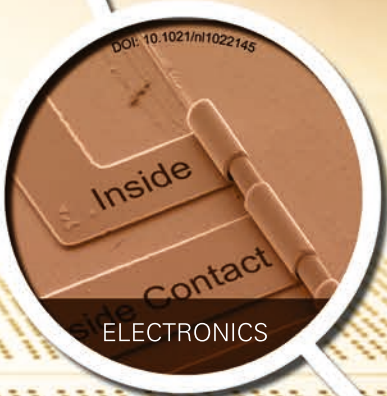
MEMS



SENSORS

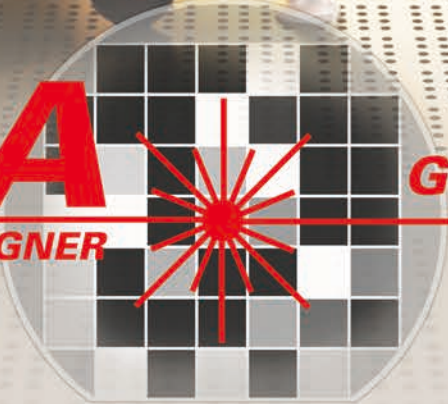


GRAY SCALE



ELECTRONICS

MLA
MASKLESS ALIGNER



GO MASKLESS
ACHIEVE MORE



STEP 1: SYSTEM SETUP

- Intuitive User Interface
- Support for all standard input formats (dxf, gdsii, cif, gerber)
- CAD Software for design creation included

MLA100

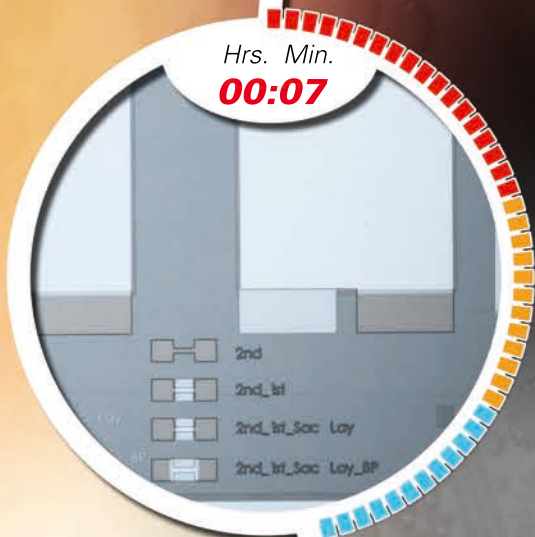


MORE INFO? SCAN THIS!



STEP 2: LOADING

- Simple loading procedure
- One chuck for all substrates from 5 x 5 mm² to 100 x 100 mm²
- Automatic substrate size detection
- No need for edge-bead removal or wedge compensation



STEP 3: ALIGNMENT

- High precision topside alignment
- Fast alignment procedure
- Simple alignment on thick resists and small substrates
- Alignment accuracy $\leq 1 \mu\text{m}$



STEP 4: EXPOSURE

- Min. feature size of 1 μm
- Exposure time for 20 x 20 mm² approx. 8 min.
- Non-contact exposure
- High Aspect ratio exposures in thick resists
- Basic gray scale exposure mode
- Compatible to g-,h- and i-line resists

MLA
MASKLESS ALIGNER



GO MASKLESS _____
_____ **ACHIEVE MORE**

Specifications depend on individual process conditions and can vary according to equipment configurations. Design and specifications are subject to change without prior notice.

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